LISTING OF CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~, in particular a stamping or laminating film, which includes at least one component produced using organic semiconductor technology, in particular one or more organic field effect transistors, wherein the component includes a plurality of layers and wherein the plurality of layers include electrical functional layers,

~~characterised in that~~

wherein one or more layers of the component are provided with a spatial structuring by means of thermal replication or UV replication, wherein at least one functional layer is partially completely severed in the region of the spatial structuring.

2. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 1, wherein ~~characterised in that~~ the film is a stamping or laminating film.

3. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 2, wherein ~~characterised in that~~ the stamping or laminating film ~~has~~ comprises:

a carrier film ~~(11, 61, 71, 81)~~,

at least one layer ~~(16, 67, 76, 88)~~ comprising an organic semiconductor element, in particular polythiophene,

at least one layer ~~(15, 65, 75, 87)~~ comprising an electrically insulating material, and

two or more layers ~~(14, 17, 19, 64, 66, 74, 77, 86, 89)~~ which are shaped in a pattern configuration in region-wise manner and which comprise an electrically conductive material.

4. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 3, wherein ~~characterised in that~~ the electrically conductive layers ~~(14, 17, 19, 64, 66, 74, 77, 86, 89)~~ comprise an organic conductive material, in particular polyaniline or polypyrrole.

5. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 3, wherein ~~or claim 4 characterised in that~~ the electrically insulating layer ~~(15, 65, 75, 87)~~ comprises an organic insulation material, in particular polyvinylphenol.

6. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 2, wherein ~~one of claims 2 through 5 characterised in that~~ the film is a stamping film which has a carrier film ~~(11)~~ and a transfer layer portion ~~(2)~~ which is applied to the carrier film ~~(11)~~ and which is releasable from the carrier film ~~(11)~~.

7. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 6, wherein ~~characterised in that~~ the stamping film has a release layer ~~(12, 62, 72, 82)~~ and an adhesive layer ~~(20, 69, 79, 97)~~.

8. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 2, wherein ~~one of claims 2 through 7 characterised in that~~ the stamping or laminating film has one or more lacquer layers ~~(13, 18, 63, 68, 73, 78, 84, 90)~~ adjoining functional polymer layers.

9. (Currently Amended) A film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 3, wherein ~~characterised in that~~ the electrically conductive layers, the layer comprising a semiconductor material and the layer comprising an electrically insulating material are transparent.

10. (Currently Amended) A film as set forth in claim 1, wherein ~~characterised in that~~ the film is a film element ~~(2)~~ which has a layer comprising:

an organic semiconductor material ~~(16)~~, in particular polythiophene,

a layer ~~(15)~~ comprising an electrically insulating material, and

two or more layers which comprise an electrically conductive material ~~(14, 17, 19)~~ and which are shaped in a pattern configuration in region-wise manner.

11. (Currently Amended) A film as set forth in claim 10, wherein ~~characterised in that~~ the film ~~(2)~~ is a film element which is applied to a substrate by means of a stamping or laminating film ~~(1), in particular as set forth in one of claims 2 through 9~~.

12. (Currently Amended) A film ~~(8)~~ as set forth in claim 1, wherein ~~characterised in that one of the preceding claims characterised in that~~ an electrical functionality, in particular that

of at least one electrical component produced using organic semiconductor technology, is combined with optical features.

13. (Currently Amended) A film ~~(8)~~ as set forth in claim 12, wherein ~~characterised in that~~ the film has a spatial structure ~~(47)~~ which is shaped between layers of the film and which on the one hand structures in a pattern configuration a layer ~~(46)~~ of the electronic component produced using organic semiconductor technology and on the other hand generates an optical-diffraction effect as an optical feature.

14. (Currently Amended) A film as set forth in claim 13, wherein ~~characterised in that~~ the spatial structure ~~(47)~~ is formed by a superimposition of a microstructure and a macrostructure, wherein the macrostructure serves for the patterned structuring of a layer ~~(46)~~ of the electronic component produced using organic semiconductor technology and the microstructure serves for the generation of the optical feature.

15. (Currently Amended) A film ~~(8)~~ as set forth in claim 1, wherein ~~one of the preceding claims characterised in that~~ the film has a holographic-optical or diffractive layer ~~(83, 84, 90, 91)~~.

16. (Currently Amended) A film ~~(8)~~ as set forth in claim 1, wherein ~~one of the preceding claims characterised in that~~ the film has a thin-film layer sequence ~~(94, 95)~~.

17. (Currently Amended) A film as set forth in claim 1, wherein ~~one of the preceding claims characterised in that~~ the film has a decoration layer.

18. (Currently Amended) A film ~~(8)~~ as set forth in claim 1, wherein ~~one of the preceding claims characterised in that~~ the film ~~(8)~~ has two or more mutually superposed layers ~~(83, 84, 90, 91, 94, 95)~~ which generate an optical security feature, wherein one or more functional layers ~~(86, 87, 88, 89)~~ of the electronic component produced using organic semiconductor technology are arranged between such optically active layers.

19. (Currently Amended) A film as set forth in claim 1, wherein ~~one of the preceding claims characterised in that~~ the film is used as a security element.

20. (Currently Amended) A process for the production of a film ~~(1, 3, 6, 7, 8, 9)~~ as set forth in claim 1, wherein ~~characterised in that~~ structuring of one or more layers ~~(43, 49, 50)~~ of the at least one component produced using organic semiconductor technology is effected by thermal replication or UV replication.

21. (Currently Amended) A process as set forth in claim 20, wherein ~~characterised in that~~ replicated into the layer ~~(42)~~ to be replicated is a spatial structure whose structure depth is greater than or equal to the thickness of the layer ~~(42)~~ to be replicated, so that the layer to be replicated is completely severed in part by the replication operation and an electrical functional

layer ~~(43)~~ which is structured in a pattern configuration in accordance with the spatial structure is formed.

22. (Currently Amended) A process as set forth in claim 21, wherein ~~characterised in that~~ such a spatial structure is replicated in an electrode layer comprising an electrically conductive material and then an electrical functional layer comprising a non-conducting or semiconducting material is applied to said layer.

23. (Currently Amended) A process as set forth in claim 20, wherein ~~characterised in that~~ replicated into the layer ~~(42)~~ to be replicated is a spatial structure whose structure depth is less than the thickness of the layer ~~(48)~~ to be replicated.

24. (Currently Amended) A process as set forth in claim 23, wherein ~~characterised in that~~ there is applied to the replicated layer ~~(46)~~ an electrical functional layer ~~(49)~~ of a material which upon hardening experiences a pre-defined reduction in volume, and that said material is applied to the replicated layer ~~(46)~~ in an application amount with which upon hardening a functional layer ~~(49)~~ which is structured in a pattern configuration in accordance with the replicated structure remains by virtue of the shrinkage in volume.

25. (Currently Amended) A process as set forth in claim 24, wherein ~~characterised in that~~ the functional layer comprises an UV-hardenable material.

26. (Currently Amended) A process as set forth in claim 23, wherein ~~characterised in that~~ an electrical functional layer ~~(50)~~ is applied to the replicated layer ~~(46)~~ and that the electrical functional layer is then removed, in particular by etching, to a depth such that there remains a functional layer ~~(50)~~ which is structured in a pattern configuration in accordance with the replicated structure.

27. (Currently Amended) A process as set forth in claim 23, wherein ~~one of claims 23 through 26 characterised in that~~ the spatial structure is replicated in an electrical functional layer comprising a non-conducting or semiconducting material and then an electrode layer comprising a conductive material is applied to said layer.

28. (Currently Amended) A process for the production of a film as set forth in claim 1, wherein ~~in particular a process as set forth in claim 20, characterised in that~~ all or one or more electrode, insulation and semiconducting layers which are required for the function of the at least one component produced using organic semiconductor technology are introduced into a film structure over the entire surface area or part of the surface area by printing processes.

29. (Currently Amended) A process as set forth in claim 20, wherein ~~one of claims 20 through 28 characterised in that~~ an electrical functionality, in particular one or more components produced using organic semiconductor technology, and an optical functionality, in particular diffractive-optical structures, are produced by a replication operation.